

Binding treatment of copper sheet with improved binding strength and bottom cutting resistant

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A treated electrodeposited copper foil having a bond-enhancing copper layer, preferably a plurality of layers, electrodeposited on a bonding side of a base copper foil, a layer of co-deposited copper and arsenic electrodeposited on the bond-enhancing layer, and a zinc or zinc alloy layer electrodeposited on the copper/arsenic layer. A process for making such foil, and a copper-clad laminate wherein such foil is bonded to a polymeric substrate.

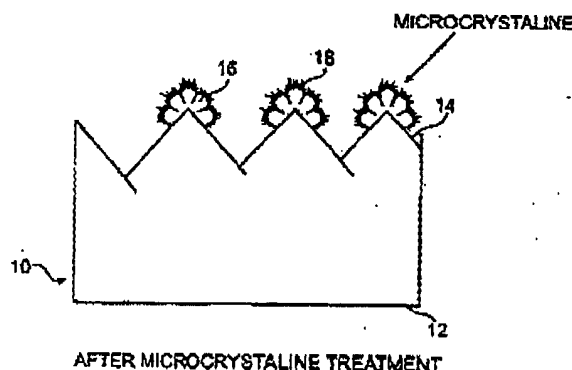


FIG. 2

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[54] 发明名称 具有改良的粘结强度和耐底切性的铜箔的粘结处理

[57] 摘要

本发明涉及一种处理的电沉积铜箔,其具有粘合—增强铜层,优选多层,其电沉积在基铜箔的粘合面上;还具有电沉积在粘合—增强层上的铜和砷共沉积层,和电沉积在铜/砷层上的锌或锌合金层。本发明还涉及一种制造这种箔和敷铜箔叠片的方法,其中这种箔被粘接到聚合物衬底上。

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